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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	ARM® Cortex®-A9
Number of Cores/Bus Width	4 Core, 32-Bit
Speed	1.0GHz
Co-Processors/DSP	Multimedia; NEON™ SIMD
RAM Controllers	LPDDR2, LVDDR3, DDR3
Graphics Acceleration	Yes
Display & Interface Controllers	Keypad, LCD
Ethernet	10/100/1000Mbps (1)
SATA	SATA 3Gbps (1)
USB	USB 2.0 + PHY (4)
Voltage - I/O	1.8V, 2.5V, 2.8V, 3.3V
Operating Temperature	-20°C ~ 105°C (TJ)
Security Features	ARM TZ, Boot Security, Cryptography, RTIC, Secure Fusebox, Secure JTAG, Secure Memory, Secure RTC, Tamper Detection
Package / Case	624-LFBGA, FCBGA
Supplier Device Package	624-FCPBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcimx6q5eym10ce

- Two Master AXI (64-bit) bus interfaces output of L2 cache
- Frequency of the core (including Neon and L1 cache) as per Table 6.
- NEON MPE coprocessor
  - SIMD Media Processing Architecture
  - NEON register file with 32x64-bit general-purpose registers
  - NEON Integer execute pipeline (ALU, Shift, MAC)
  - NEON dual, single-precision floating point execute pipeline (FADD, FMUL)
  - NEON load/store and permute pipeline

The SoC-level memory system consists of the following additional components:

- Boot ROM, including HAB (96 KB)
- Internal multimedia / shared, fast access RAM (OCRAM, 256 KB)
- Secure/non-secure RAM (16 KB)
- External memory interfaces:
  - 16-bit, 32-bit, and 64-bit DDR3-1066, DDR3L-1066, and 1/2 LPDDR2-800 channels, supporting DDR interleaving mode, for dual x32 LPDDR2
  - 8-bit NAND-Flash, including support for Raw MLC/SLC, 2 KB, 4 KB, and 8 KB page size, BA-NAND, PBA-NAND, LBA-NAND, OneNAND™ and others. BCH ECC up to 40 bit.
  - 16/32-bit NOR Flash. All EIMv2 pins are muxed on other interfaces.
  - 16/32-bit PSRAM, Cellular RAM

Each i.MX 6Dual/6Quad processor enables the following interfaces to external devices (some of them are muxed and not available simultaneously):

- Hard Disk Drives—SATA II, 3.0 Gbps
- Displays—Total five interfaces available. Total raw pixel rate of all interfaces is up to 450 Mpixels/sec, 24 bpp. Up to four interfaces may be active in parallel.
  - One Parallel 24-bit display port, up to 225 Mpixels/sec (for example, WUXGA at 60 Hz or dual HD1080 and WXGA at 60 Hz)
  - LVDS serial ports—One port up to 170 Mpixels/sec (for example, WUXGA at 60 Hz) or two ports up to 85 MP/sec each
  - HDMI 1.4 port
  - MIPI/DSI, two lanes at 1 Gbps
- Camera sensors:
  - Parallel Camera port (up to 20 bit and up to 240 MHz peak)
  - MIPI CSI-2 serial camera port, supporting up to 1000 Mbps/lane in 1/2/3-lane mode and up to 800 Mbps/lane in 4-lane mode. The CSI-2 Receiver core can manage one clock lane and up to four data lanes. Each i.MX 6Dual/6Quad processor has four lanes.
- Expansion cards:
  - Four MMC/SD/SDIO card ports all supporting:

  - 1-bit or 4-bit transfer mode specifications for SD and SDIO cards up to UHS-I SDR-104 mode (104 MB/s max)
  - 1-bit, 4-bit, or 8-bit transfer mode specifications for MMC cards up to 52 MHz in both SDR and DDR modes (104 MB/s max)
- USB:
  - One High Speed (HS) USB 2.0 OTG (Up to 480 Mbps), with integrated HS USB PHY
  - Three USB 2.0 (480 Mbps) hosts:
    - One HS host with integrated High Speed PHY
    - Two HS hosts with integrated High Speed Inter-Chip (HS-IC) USB PHY
- Expansion PCI Express port (PCIe) v2.0 one lane
  - PCI Express (Gen 2.0) dual mode complex, supporting Root complex operations and Endpoint operations. Uses x1 PHY configuration.
- Miscellaneous IPs and interfaces:
  - SSI block capable of supporting audio sample frequencies up to 192 kHz stereo inputs and outputs with I^2S mode
  - ESAI is capable of supporting audio sample frequencies up to 260 kHz in I2S mode with 7.1 multi channel outputs
  - Five UARTs, up to 5.0 Mbps each:
    - Providing RS232 interface
    - Supporting 9-bit RS485 multidrop mode
    - One of the five UARTs (UART1) supports 8-wire while the other four support 4-wire. This is due to the SoC IOMUX limitation, because all UART IPs are identical.
  - Five eCSPI (Enhanced CSPI)
  - Three I2C, supporting 400 kbps
  - Gigabit Ethernet Controller (IEEE1588 compliant), 10/100/1000[1] Mbps
  - Four Pulse Width Modulators (PWM)
  - System JTAG Controller (SJC)
  - GPIO with interrupt capabilities
  - 8x8 Key Pad Port (KPP)
  - Sony Philips Digital Interconnect Format (SPDIF), Rx and Tx
  - Two Controller Area Network (FlexCAN), 1 Mbps each
  - Two Watchdog timers (WDOG)
  - Audio MUX (AUDMUX)
  - MLB (MediaLB) provides interface to MOST Networks (150 Mbps) with the option of DTCP cipher accelerator

1. The theoretical maximum performance of 1 Gbps ENET is limited to 470 Mbps (total for Tx and Rx) due to internal bus throughput limitations. The actual measured performance in optimized environment is up to 400 Mbps. For details, see the ERR004512 erratum in the i.MX 6Dual/6Quad errata document (IMX6DQCE).

3 Modules List

The i.MX 6Dual/6Quad processors contain a variety of digital and analog modules. Table 2 describes these modules in alphabetical order.

Table 2. i.MX 6Dual/6Quad Modules List

Block Mnemonic	Block Name	Subsystem	Brief Description
512 x 8 Fuse Box	Electrical Fuse Array	Security	Electrical Fuse Array. Enables to setup Boot Modes, Security Levels, Security Keys, and many other system parameters. The i.MX 6Dual/6Quad processors consist of 512x8-bit fuse box accessible through OCOTP_CTRL interface.
APBH-DMA	NAND Flash and BCH ECC DMA Controller	System Control Peripherals	DMA controller used for GPMI2 operation.
ARM	ARM Platform	ARM	The ARM Cortex-A9 platform consists of 4x (four) Cortex-A9 cores version r2p10 and associated sub-blocks, including Level 2 Cache Controller, SCU (Snoop Control Unit), GIC (General Interrupt Controller), private timers, Watchdog, and CoreSight debug modules.
ASRC	Asynchronous Sample Rate Converter	Multimedia Peripherals	The Asynchronous Sample Rate Converter (ASRC) converts the sampling rate of a signal associated to an input clock into a signal associated to a different output clock. The ASRC supports concurrent sample rate conversion of up to 10 channels of about -120dB THD+N. The sample rate conversion of each channel is associated to a pair of incoming and outgoing sampling rates. The ASRC supports up to three sampling rate pairs.
AUDMUX	Digital Audio Mux	Multimedia Peripherals	The AUDMUX is a programmable interconnect for voice, audio, and synchronous data routing between host serial interfaces (for example, SSI1, SSI2, and SSI3) and peripheral serial interfaces (audio and voice codecs). The AUDMUX has seven ports with identical functionality and programming models. A desired connectivity is achieved by configuring two or more AUDMUX ports.
BCH40	Binary-BCH ECC Processor	System Control Peripherals	The BCH40 module provides up to 40-bit ECC error correction for NAND Flash controller (GPMI).
CAAM	Cryptographic Accelerator and Assurance Module	Security	CAAM is a cryptographic accelerator and assurance module. CAAM implements several encryption and hashing functions, a run-time integrity checker, and a Pseudo Random Number Generator (PRNG). The pseudo random number generator is certified by Cryptographic Algorithm Validation Program (CAVP) of National Institute of Standards and Technology (NIST). Its DRBG validation number is 94 and its SHS validation number is 1455. CAAM also implements a Secure Memory mechanism. In i.MX 6Dual/6Quad processors, the security memory provided is 16 KB.
CCM GPC SRC	Clock Control Module, General Power Controller, System Reset Controller	Clocks, Resets, and Power Control	These modules are responsible for clock and reset distribution in the system, and also for the system power management.

Table 2. i.MX 6Dual/6Quad Modules List (continued)

Block Mnemonic	Block Name	Subsystem	Brief Description
LDB	LVDS Display Bridge	Connectivity Peripherals	LVDS Display Bridge is used to connect the IPU (Image Processing Unit) to External LVDS Display Interface. LDB supports two channels; each channel has following signals: • One clock pair • Four data pairs Each signal pair contains LVDS special differential pad (PadP, PadM).
MLB150	MediaLB	Connectivity / Multimedia Peripherals	The MLB interface module provides a link to a MOST® data network, using the standardized MediaLB protocol (up to 150 Mbps). The module is backward compatible to MLB-50.
MMDC	Multi-Mode DDR Controller	Connectivity Peripherals	DDR Controller has the following features: • Supports 16/32/64-bit DDR3 / DDR3L or LPDDR2 • Supports both dual x32 for LPDDR2 and x64 DDR3 / LPDDR2 configurations (including 2x32 interleaved mode) • Supports up to 4 GByte DDR memory space
OCOTP_CTRL	OTP Controller	Security	The On-Chip OTP controller (OCOTP_CTRL) provides an interface for reading, programming, and/or overriding identification and control information stored in on-chip fuse elements. The module supports electrically-programmable poly fuses (eFUSEs). The OCOTP_CTRL also provides a set of volatile software-accessible signals that can be used for software control of hardware elements, not requiring non-volatility. The OCOTP_CTRL provides the primary user-visible mechanism for interfacing with on-chip fuse elements. Among the uses for the fuses are unique chip identifiers, mask revision numbers, cryptographic keys, JTAG secure mode, boot characteristics, and various control signals, requiring permanent non-volatility.
OCRAM	On-Chip Memory Controller	Data Path	The On-Chip Memory controller (OCRAM) module is designed as an interface between system's AXI bus and internal (on-chip) SRAM memory module. In i.MX 6Dual/6Quad processors, the OCRAM is used for controlling the 256 KB multimedia RAM through a 64-bit AXI bus.
OSC 32 kHz	OSC 32 kHz	Clocking	Generates 32.768 kHz clock from an external crystal.
PCIe	PCI Express 2.0	Connectivity Peripherals	The PCIe IP provides PCI Express Gen 2.0 functionality.
PMU	Power-Management Functions	Data Path	Integrated power management unit. Used to provide power to various SoC domains.
PWM-1 PWM-2 PWM-3 PWM-4	Pulse Width Modulation	Connectivity Peripherals	The pulse-width modulator (PWM) has a 16-bit counter and is optimized to generate sound from stored sample audio images and it can also generate tones. It uses 16-bit resolution and a 4x16 data FIFO to generate sound.
RAM 16 KB	Secure/non-secure RAM	Secured Internal Memory	Secure/non-secure Internal RAM, interfaced through the CAAM.
RAM 256 KB	Internal RAM	Internal Memory	Internal RAM, which is accessed through OCRAM memory controllers.

Table 2. i.MX 6Dual/6Quad Modules List (continued)

Block Mnemonic	Block Name	Subsystem	Brief Description
SSI-1 SSI-2 SSI-3	I2S/SSI/AC97 Interface	Connectivity Peripherals	The SSI is a full-duplex synchronous interface, which is used on the processor to provide connectivity with off-chip audio peripherals. The SSI supports a wide variety of protocols (SSI normal, SSI network, I2S, and AC-97), bit depths (up to 24 bits per word), and clock / frame sync options. The SSI has two pairs of 8x24 FIFOs and hardware support for an external DMA controller to minimize its impact on system performance. The second pair of FIFOs provides hardware interleaving of a second audio stream that reduces CPU overhead in use cases where two time slots are being used simultaneously.
TEMPMON	Temperature Monitor	System Control Peripherals	The temperature monitor/sensor IP module for detecting high temperature conditions. The temperature read out does not reflect case or ambient temperature. It reflects the temperature in proximity of the sensor location on the die. Temperature distribution may not be uniformly distributed; therefore, the read out value may not be the reflection of the temperature value for the entire die.
TZASC	Trust-Zone Address Space Controller	Security	The TZASC (TZC-380 by ARM) provides security address region control functions required for intended application. It is used on the path to the DRAM controller.
UART-1 UART-2 UART-3 UART-4 UART-5	UART Interface	Connectivity Peripherals	Each of the UARTv2 modules support the following serial data transmit/receive protocols and configurations: • 7- or 8-bit data words, 1 or 2 stop bits, programmable parity (even, odd or none) • Programmable baud rates up to 5 MHz • 32-byte FIFO on Tx and 32 half-word FIFO on Rx supporting auto-baud • IrDA 1.0 support (up to SIR speed of 115200 bps) • Option to operate as 8-pins full UART, DCE, or DTE
USBOH3A	USB 2.0 High Speed OTG and 3x HS Hosts	Connectivity Peripherals	USBOH3 contains: • One high-speed OTG module with integrated HS USB PHY • One high-speed Host module with integrated HS USB PHY • Two identical high-speed Host modules connected to HSIC USB ports.

Table 8. Maximum Supply Currents (continued)

Power Supply	Conditions	Maximum Current		Unit
		Power Virus	CoreMark	
NVCC_LVDS2P5	—	NVCC_LVDS2P5 is connected to VDD_HIGH_CAP at the board level. VDD_HIGH_CAP is capable of handing the current required by NVCC_LVDS2P5.		
MISC				
DRAM_VREF	—	1		mA

1 The actual maximum current drawn from VDD_HIGH_IN will be as shown plus any additional current drawn from the VDD_HIGH_CAP outputs, depending upon actual application configuration (for example, NVCC_LVDS_2P5, NVCC_MIPI, or HDMI, PCIe, and SATA VPH supplies).

2 Under normal operating conditions, the maximum current on VDD_SNVS_IN is shown Table 8. The maximum VDD_SNVS_IN current may be higher depending on specific operating configurations, such as BOOT_MODE[1:0] not equal to 00, or use of the Tamper feature. During initial power on, VDD_SNVS_IN can draw up to 1 mA if the supply is capable of sourcing that current. If less than 1 mA is available, the VDD_SNVS_CAP charge time will increase.

3 This is the maximum current per active USB physical interface.

4 The DRAM power consumption is dependent on several factors such as external signal termination. DRAM power calculators are typically available from memory vendors which take into account factors such as signal termination.
See the *i.MX 6Dual/6Quad Power Consumption Measurement Application Note* (AN4509) for examples of DRAM power consumption during specific use case scenarios.

5 General equation for estimated, maximum power consumption of an IO power supply:
Imax = N x C x V x (0.5 x F)
Where:
N—Number of IO pins supplied by the power line
C—Equivalent external capacitive load
V—IO voltage
(0.5 xF)—Data change rate. Up to 0.5 of the clock rate (F)
In this equation, Imax is in Amps, C in Farads, V in Volts, and F in Hertz.

4.1.6 Low Power Mode Supply Currents

Table 9 shows the current core consumption (not including I/O) of the i.MX 6Dual/6Quad processors in selected low power modes.

Table 9. Stop Mode Current and Power Consumption

Mode	Test Conditions	Supply	Typical[1]	Unit
WAIT	• ARM, SoC, and PU LDOs are set to 1.225 V • HIGH LDO set to 2.5 V • Clocks are gated • DDR is in self refresh • PLLs are active in bypass (24 MHz) • Supply voltages remain ON	VDD_ARM_IN (1.4 V)	6	mA
		VDD_SOC_IN (1.4 V)	23	mA
		VDD_HIGH_IN (3.0 V)	3.7	mA
		Total	52	mW

4.1.7 USB PHY Current Consumption

4.1.7.1 Power Down Mode

In power down mode, everything is powered down, including the VBUS valid detectors, typical condition. Table 10 shows the USB interface current consumption in power down mode.

Table 10. USB PHY Current Consumption in Power Down Mode

	VDD_USB_CAP (3.0 V)	VDD_HIGH_CAP (2.5 V)	NVCC_PLL_OUT (1.1 V)
Current	5.1 µA	1.7 µA	<0.5 µA

NOTE

The currents on the VDD_HIGH_CAP and VDD_USB_CAP were identified to be the voltage divider circuits in the USB-specific level shifters.

4.1.8 SATA Typical Power Consumption

Table 11 provides SATA PHY currents for certain Tx operating modes.

NOTE

Tx power consumption values are provided for a single transceiver. If T = single transceiver power and C = Clock module power, the total power required for N lanes = N x T + C.

Table 11. SATA PHY Current Drain

Mode	Test Conditions	Supply	Typical Current	Unit
P0: Full-power state[1]	Single Transceiver	SATA_VP	11	mA
		SATA_VPH	13	
	Clock Module	SATA_VP	6.9	
		SATA_VPH	6.2	
P0: Mobile[2]	Single Transceiver	SATA_VP	11	mA
		SATA_VPH	11	
	Clock Module	SATA_VP	6.9	
		SATA_VPH	6.2	
P0s: Transmitter idle	Single Transceiver	SATA_VP	9.4	mA
		SATA_VPH	2.9	
	Clock Module	SATA_VP	6.9	
		SATA_VPH	6.2	

4.2 Power Supplies Requirements and Restrictions

The system design must comply with power-up sequence, power-down sequence, and steady state guidelines as described in this section to ensure the reliable operation of the device. Any deviation from these sequences may result in the following situations:

- Excessive current during power-up phase
- Prevention of the device from booting
- Irreversible damage to the processor

4.2.1 Power-Up Sequence

For power-up sequence, the restrictions are as follows:

- VDD_SNVS_IN supply must be turned ON before any other power supply. It may be connected (shorted) with VDD_HIGH_IN supply.
- If a coin cell is used to power VDD_SNVS_IN, then ensure that it is connected before any other supply is switched on.
- The SRC_POR_B signal controls the processor POR and must be immediately asserted at power-up and remain asserted until the VDD_ARM_CAP, VDD_SOC_CAP, and VDD_PU_CAP supplies are stable. VDD_ARM_IN and VDD_SOC_IN may be applied in either order with no restrictions.

  Ensure that there is no back voltage (leakage) from any supply on the board towards the 3.3 V supply (for example, from the external components that use both the 1.8 V and 3.3 V supplies).

  NOTE

  USB_OTG_VBUS and USB_H1_VBUS are not part of the power supply sequence and can be powered at any time.

4.2.2 Power-Down Sequence

There are no special restrictions for i.MX 6Dual/6Quad SoC.

4.2.3 Power Supplies Usage

- All I/O pins must not be externally driven while the I/O power supply for the pin (NVCC_xxx) is OFF. This can cause internal latch-up and malfunctions due to reverse current flows. For information about I/O power supply of each pin, see the “Power Group” column of Table 96, “21 x 21 mm Functional Contact Assignments”.
- When the SATA interface is not used, the SATA_VP and SATA_VPH supplies should be grounded. The input and output supplies for rest of the ports (SATA_REXT, SATA_PHY_RX_N, SATA_PHY_RX_P, and SATA_PHY_TX_N) can remain unconnected. It is recommended not to turn OFF the SATA_VPH supply while the SATA_VP supply is ON, as it may lead to excessive power consumption. If boundary scan test is used, SATA_VP and SATA_VPH must remain powered.

CAUTION

The internal RTC oscillator does not provide an accurate frequency and is affected by process, voltage, and temperature variations. NXP strongly recommends using an external crystal as the RTC_XTALI reference. If the internal oscillator is used instead, careful consideration must be given to the timing implications on all of the SoC modules dependent on this clock.

The OSC32k runs from VDD_SNVS_CAP, which comes from the VDD_HIGH_IN/VDD_SNVS_IN power mux.

Table 20. OSC32K Main Characteristics

Parameter	Min	Typ	Max	Comments
Fosc	—	32.768 kHz	—	This frequency is nominal and determined mainly by the crystal selected. 32.0 K would work as well.
Current consumption	—	4 μA	—	The typical value shown is only for the oscillator, driven by an external crystal. If the internal ring oscillator is used instead of an external crystal, then approximately 25 μA must be added to this value.
Bias resistor	—	14 MΩ	—	This the integrated bias resistor that sets the amplifier into a high gain state. Any leakage through the ESD network, external board leakage, or even a scope probe that is significant relative to this value will debias the amplifier. The debiasing will result in low gain, and will impact the circuit's ability to start up and maintain oscillations.
Target Crystal Properties				
Cload	—	10 pF	—	Usually crystals can be purchased tuned for different Cloads. This Cload value is typically 1/2 of the capacitances realized on the PCB on either side of the quartz. A higher Cload will decrease oscillation margin, but increases current oscillating through the crystal.
ESR	—	50 kΩ	100 kΩ	Equivalent series resistance of the crystal. Choosing a crystal with a higher value will decrease the oscillating margin.

4.6 I/O DC Parameters

This section includes the DC parameters of the following I/O types:

- General Purpose I/O (GPIO)
- Double Data Rate I/O (DDR) for LPDDR2 and DDR3/DDR3L modes
- LVDS I/O
- MLB I/O

NOTE

The term ‘OVDD’ in this section refers to the associated supply rail of an input or output.

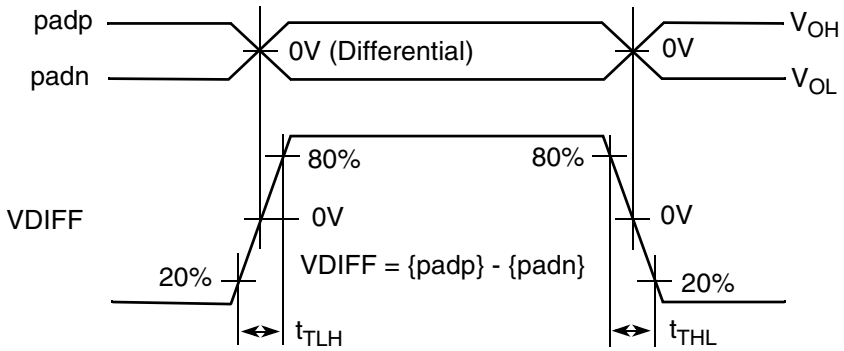


Figure 7. Differential MLB Driver Transition Time Waveform

A 4-stage pipeline is used in the MLB 6-pin implementation to facilitate design, maximize throughput, and allow for reasonable PCB trace lengths. Each cycle is one ipp_clk_in* (internal clock from MLB PLL) clock period. Cycles 2, 3, and 4 are MLB PHY related. Cycle 2 includes clock-to-output delay of Signal/Data sampling flip-flop and Transmitter, Cycle 3 includes clock-to-output delay of Signal/Data clocked receiver, Cycle 4 includes clock-to-output delay of Signal/Data sampling flip-flop.

MLB 6-pin pipeline diagram is shown in Figure 8.

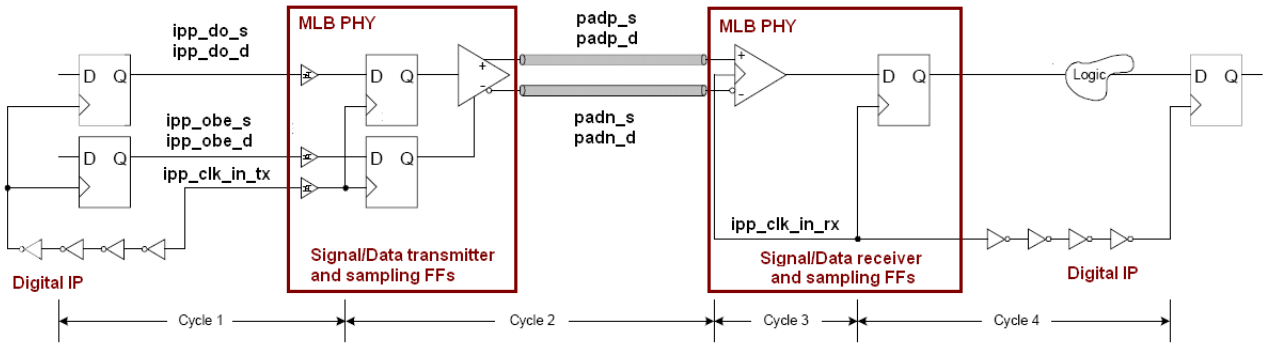


Figure 8. MLB 6-Pin Pipeline Diagram

Table 33 shows the AC parameters for MLB I/O.

Table 33. I/O AC Parameters of MLB PHY

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Differential pulse skew[1]	t_{SKD}	Rload = 50 Ω between padP and padN	—	—	0.1	ns
Transition Low to High Time[2]	t_{TLH}		—	—	1	
Transition High to Low Time	t_{THL}		—	—	1	
MLB external clock Operating Frequency	fclk_ext	—	—	—	102.4	MHz
MLB PLL clock Operating Frequency	fclk_pll	—	—	—	307.2	MHz

1 $t_{SKD} = | t_{PHLD} - t_{PLHD} |$, is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

2 Measurement levels are 20-80% from output voltage.

4.8 Output Buffer Impedance Parameters

This section defines the I/O impedance parameters of the i.MX 6Dual/6Quad processors for the following I/O types:

- General Purpose I/O (GPIO)
- Double Data Rate I/O (DDR) for LPDDR2, and DDR3 modes
- LVDS I/O
- MLB I/O

NOTE

GPIO and DDR I/O output driver impedance is measured with “long” transmission line of impedance Ztl attached to I/O pad and incident wave launched into transmission line. Rpu/Rpd and Ztl form a voltage divider that defines specific voltage of incident wave relative to OVDD. Output driver impedance is calculated from this voltage divider (see Figure 9).

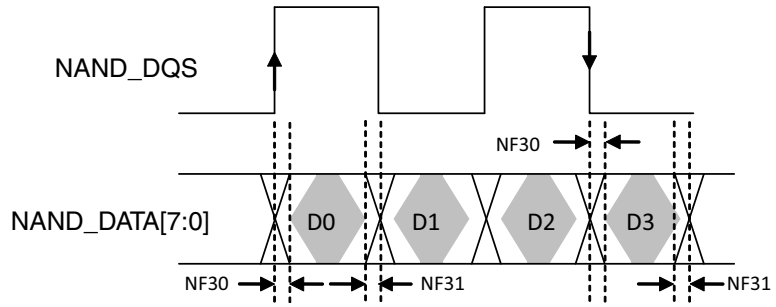


Figure 32. NAND_DQS/NAND_DQ Read Valid Window

Table 45. Source Synchronous Mode Timing Parameters[1]

ID	Parameter	Symbol	Timing T = GPMI Clock Cycle		Unit
			Min	Max	
NF18	NAND_CEx_B access time	tCE	CE_DELAY × T - 0.79 [see 2]		ns
NF19	NAND_CEx_B hold time	tCH	0.5 × tCK - 0.63 [see 2]		ns
NF20	Command/address NAND_DATAxx setup time	tCAS	0.5 × tCK - 0.05		ns
NF21	Command/address NAND_DATAxx hold time	tCAH	0.5 × tCK - 1.23		ns
NF22	clock period	tCK	—		ns
NF23	preamble delay	tPRE	PRE_DELAY × T - 0.29 [see 2]		ns
NF24	postamble delay	tPOST	POST_DELAY × T - 0.78 [see 2]		ns
NF25	NAND_CLE and NAND_ALE setup time	tCALS	0.5 × tCK - 0.86		ns
NF26	NAND_CLE and NAND_ALE hold time	tCALH	0.5 × tCK - 0.37		ns
NF27	NAND_CLK to first NAND_DQS latching transition	tDQSS	T - 0.41 [see 2]		ns
NF28	Data write setup	tDS	0.25 × tCK - 0.35		—
NF29	Data write hold	tDH	0.25 × tCK - 0.85		—
NF30	NAND_DQS/NAND_DQ read setup skew	tDQSQ	—	2.06	—
NF31	NAND_DQS/NAND_DQ read hold skew	tQHS	—	1.95	—

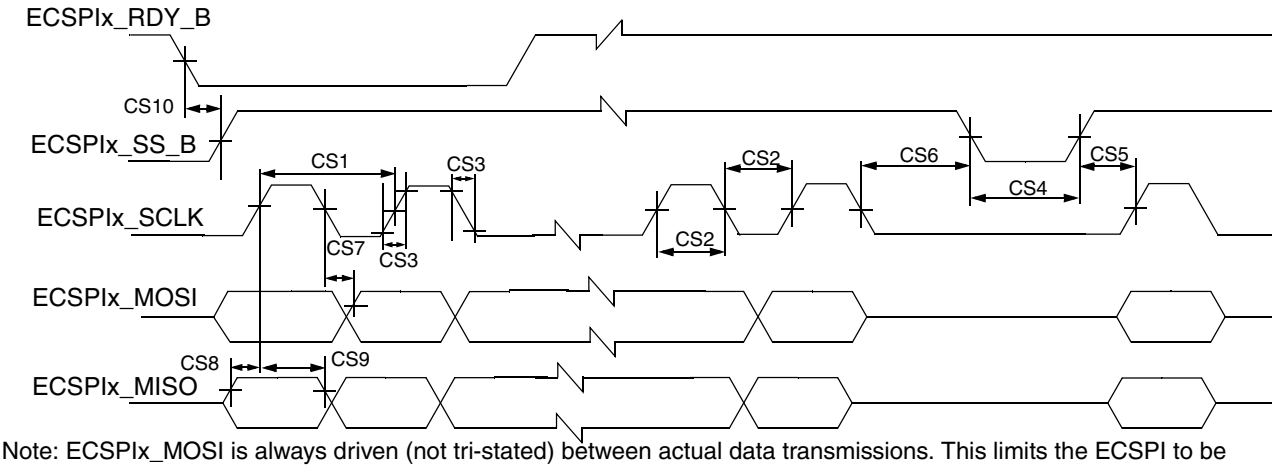
1 The GPMI source synchronous mode output timing can be controlled by the module's internal registers GPMI_TIMING2_CE_DELAY, GPMI_TIMING_PREAMBLE_DELAY, GPMI_TIMING2_POST_DELAY. This AC timing depends on these registers settings. In the table, CE_DELAY/PRE_DELAY/POST_DELAY represents each of these settings.

2 T = tCK (GPMI clock period) -0.075ns (half of maximum p-p jitter).

Figure 32 shows the timing diagram of NAND_DQS/NAND_DATAxx read valid window. For Source Synchronous mode, the typical value of tDQSQ is 0.85 ns (max) and 1 ns (max) for tQHS at 200MB/s. GPMI will sample NAND_DATA[7:0] at both rising and falling edge of a delayed NAND_DQS signal, which can be provided by an internal DPLL. The delay value can be controlled by GPMI register GPMI_READ_DDR_DLL_CTRL.SLV_DLY_TARGET (see the GPMI chapter of the i.MX 6Dual/6Quad reference manual (IMX6DQRM)). Generally, the typical delay value of this register is equal to 0x7 which means 1/4 clock cycle delay expected. However, if the board delay is large enough and cannot be ignored, the delay value should be made larger to compensate the board delay.

4.12.2.1 ECSPI Master Mode Timing

Figure 35 depicts the timing of ECSPI in master mode and Table 47 lists the ECSPI master mode timing characteristics.



Note: ECSPIx_MOSI is always driven (not tri-stated) between actual data transmissions. This limits the ECSPI to be connected between a single master and a single slave.

Figure 35. ECSPI Master Mode Timing Diagram

Table 47. ECSPI Master Mode Timing Parameters

ID	Parameter	Symbol	Min	Max	Unit
CS1	ECSPIx_SCLK Cycle Time–Read • Slow group[1] • Fast group[2] ECSPIx_SCLK Cycle Time–Write	t_{clk}	 55 40 15	—	ns
CS2	ECSPIx_SCLK High or Low Time–Read • Slow group[1] • Fast group[2] ECSPIx_SCLK High or Low Time–Write	t_{SW}	 26 20 7	—	ns
CS3	ECSPIx_SCLK Rise or Fall[3]	$t_{RISE/FALL}$	—	—	ns
CS4	ECSPIx_SSx pulse width	t_{CSLH}	Half ECSPIx_SCLK period	—	ns
CS5	ECSPIx_SSx Lead Time (CS setup time)	t_{SCS}	Half ECSPIx_SCLK period - 4	—	ns
CS6	ECSPIx_SSx Lag Time (CS hold time)	t_{HCS}	Half ECSPIx_SCLK period - 2	—	ns
CS7	ECSPIx_MOSI Propagation Delay (C_{LOAD} = 20 pF)	t_{PDmosi}	-1	1	ns
CS8	ECSPIx_MISO Setup Time • Slow group[1] • Fast group[2]	t_{Smiso}	 21.5 16	—	ns
CS9	ECSPIx_MISO Hold Time	t_{Hmiso}	0	—	ns
CS10	ECSPIx_RDY to ECSPIx_SSx Time[4]	t_{SDRY}	5	—	ns

1 ECSPI slow includes:

ECSPI1/DISP0_DAT22, ECSPI1/KEY_COL1, ECSPI1/CSI0_DAT6, ECSPI2/EIM_OE, ECSPI2/ ECSPI2/CSI0_DAT10, ECSPI3/DISP0_DAT2

2 ECSPI fast includes:

ECSPI1/EIM_D17, ECSPI4/EIM_D22, ECSPI5/SD2_DAT0, ECSPI5/SD1_DAT0

3 See specific I/O AC parameters Section 4.7, “I/O AC Parameters.”

4 ECSPI_RDY is sampled internally by ipg_clk and is asynchronous to all other CSPI signals.

Table 49. Enhanced Serial Audio Interface (ESAI) Timing (continued)

ID	Parameter[1,2]	Symbol	Expression[2]	Min	Max	Condition[3]	Unit
81	ESAI_TX_CLK rising edge to ESAI_TX_FS out (wr) low[5]	— —	— —	— —	22.0 12.0	x ck i ck	ns
82	ESAI_TX_CLK rising edge to ESAI_TX_FS out (wl) high	— —	— —	— —	19.0 9.0	x ck i ck	ns
83	ESAI_TX_CLK rising edge to ESAI_TX_FS out (wl) low	— —	— —	— —	20.0 10.0	x ck i ck	ns
84	ESAI_TX_CLK rising edge to data out enable from high impedance	— —	— —	— —	22.0 17.0	x ck i ck	ns
86	ESAI_TX_CLK rising edge to data out valid	— —	— —	— —	19.0 13.0	x ck i ck	ns
87	ESAI_TX_CLK rising edge to data out high impedance [67]	— —	— —	— —	21.0 16.0	x ck i ck	ns
89	ESAI_TX_FS input (bl, wr) setup time before ESAI_TX_CLK falling edge[5]	— —	— —	2.0 18.0	— —	x ck i ck	ns
90	ESAI_TX_FS input (wl) setup time before ESAI_TX_CLK falling edge	— —	— —	2.0 18.0	— —	x ck i ck	ns
91	ESAI_TX_FS input hold time after ESAI_TX_CLK falling edge	— —	— —	4.0 5.0	— —	x ck i ck	ns
95	ESAI_RX_HF_CLK/ESAI_TX_HF_CLK clock cycle	—	$2 \times T_C$	15	—	—	ns
96	ESAI_TX_HF_CLK input rising edge to ESAI_TX_CLK output	—	—	—	18.0	—	ns
97	ESAI_RX_HF_CLK input rising edge to ESAI_RX_CLK output	—	—	—	18.0	—	ns

1 i ck = internal clock
x ck = external clock
i ck a = internal clock, asynchronous mode
(asynchronous implies that ESAI_TX_CLK and ESAI_RX_CLK are two different clocks)
i ck s = internal clock, synchronous mode
(synchronous implies that ESAI_TX_CLK and ESAI_RX_CLK are the same clock)

2 bl = bit length
wl = word length
wr = word length relative

3 ESAI_TX_CLK(ESAI_TX_CLK pin) = transmit clock
ESAI_RX_CLK(ESAI_RX_CLK pin) = receive clock
ESAI_TX_FS(ESAI_TX_FS pin) = transmit frame sync
ESAI_RX_FS(ESAI_RX_FS pin) = receive frame sync
ESAI_TX_HF_CLK(ESAI_TX_HF_CLK pin) = transmit high frequency clock
ESAI_RX_HF_CLK(ESAI_RX_HF_CLK pin) = receive high frequency clock

4 For the internal clock, the external clock cycle is defined by Icyc and the ESAI control register.

5 The word-relative frame sync signal waveform relative to the clock operates in the same manner as the bit-length frame sync signal waveform, but it spreads from one serial clock before the first bit clock (like the bit length frame sync signal), until the second-to-last bit clock of the first word in the frame.

6 Periodically sampled and not 100% tested.

4.12.5.2 RMII Mode Timing

In RMII mode, ENET_CLK is used as the REF_CLK, which is a 50 MHz ± 50 ppm continuous reference clock. ENET_RX_EN is used as the ENET_RX_EN in RMII. Other signals under RMII mode include ENET_TX_EN, ENET0_TXD[1:0], ENET_RXD[1:0] and ENET_RX_ER.

Figure 46 shows RMII mode timings. Table 57 describes the timing parameters (M16–M21) shown in the figure.

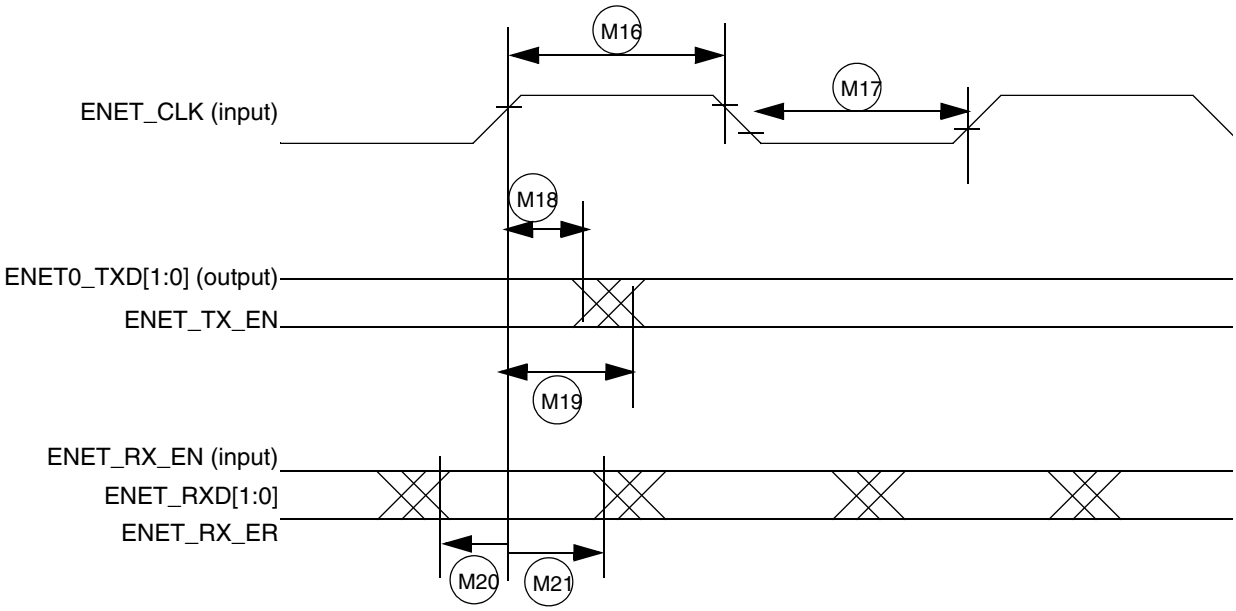


Figure 46. RMII Mode Signal Timing Diagram

Table 57. RMII Signal Timing

ID	Characteristic	Min	Max	Unit
M16	ENET_CLK pulse width high	35%	65%	ENET_CLK period
M17	ENET_CLK pulse width low	35%	65%	ENET_CLK period
M18	ENET_CLK to ENET0_TXD[1:0], ENET_TX_EN invalid	4	—	ns
M19	ENET_CLK to ENET0_TXD[1:0], ENET_TX_EN valid	—	13.5	ns
M20	ENET_RXD[1:0], ENET_RX_EN(ENET_RX_EN), ENET_RX_ER to ENET_CLK setup	4	—	ns
M21	ENET_CLK to ENET_RXD[1:0], ENET_RX_EN, ENET_RX_ER hold	2	—	ns

4.12.13.3 Receiver Real-Time Data Flow

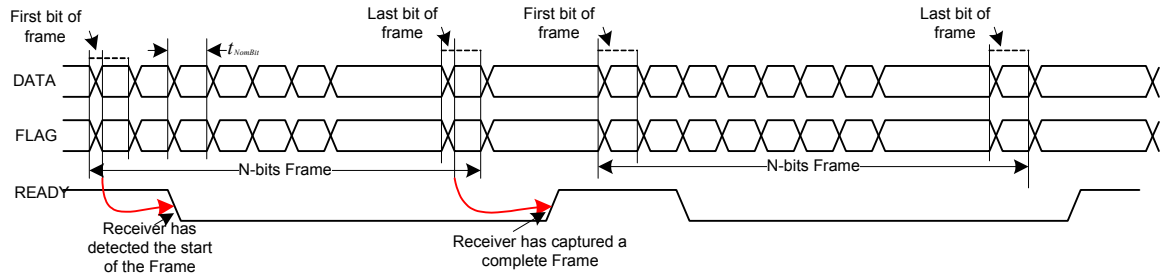


Figure 75. Receiver Real-Time Data Flow READY Signal Timing

4.12.13.4 Synchronized Data Flow Transmission with Wake

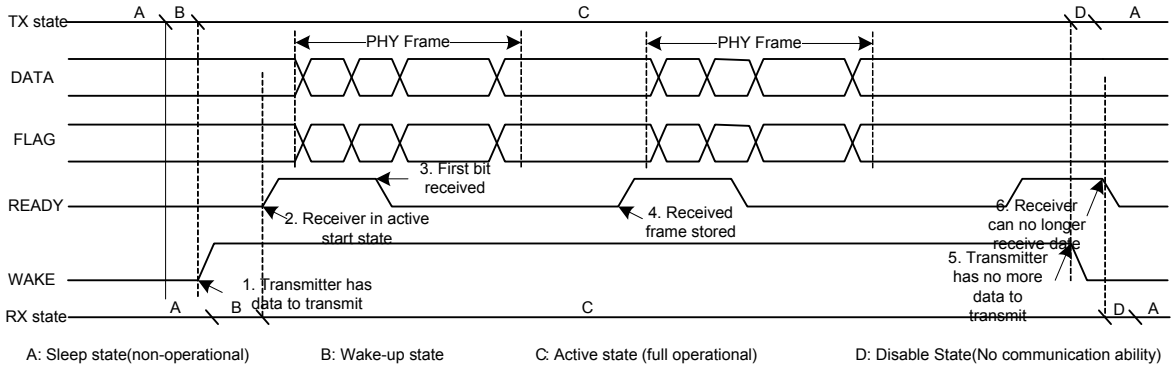


Figure 76. Synchronized Data Flow Transmission with WAKE

4.12.13.5 Stream Transmission Mode Frame Transfer

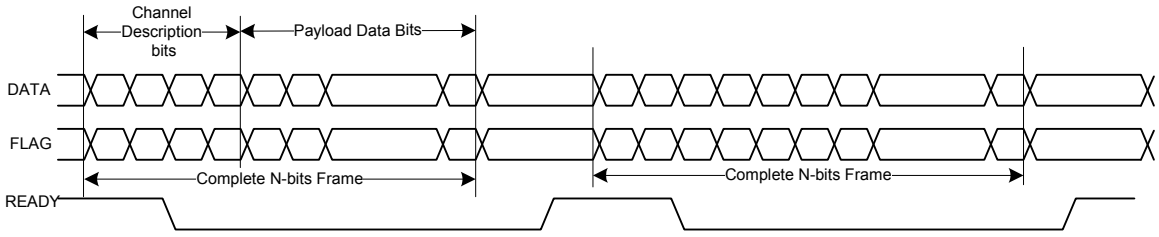


Figure 77. Stream Transmission Mode Frame Transfer (Synchronized Data Flow)

4.12.20 SSI Timing Parameters

This section describes the timing parameters of the SSI module. The connectivity of the serial synchronous interfaces are summarized in Table 81.

Table 81. AUDMUX Port Allocation

Port	Signal Nomenclature	Type and Access
AUDMUX port 1	SSI 1	Internal
AUDMUX port 2	SSI 2	Internal
AUDMUX port 3	AUD3	External – AUD3 I/O
AUDMUX port 4	AUD4	External – EIM or CSPI1 I/O through IOMUXC
AUDMUX port 5	AUD5	External – EIM or SD1 I/O through IOMUXC
AUDMUX port 6	AUD6	External – EIM or DISP2 through IOMUXC
AUDMUX port 7	SSI 3	Internal

NOTE

The terms WL and BL used in the timing diagrams and tables refer to Word Length (WL) and Bit Length (BL).

4.12.20.1 SSI Transmitter Timing with Internal Clock

Figure 90 depicts the SSI transmitter internal clock timing and Table 82 lists the timing parameters for the SSI transmitter internal clock.

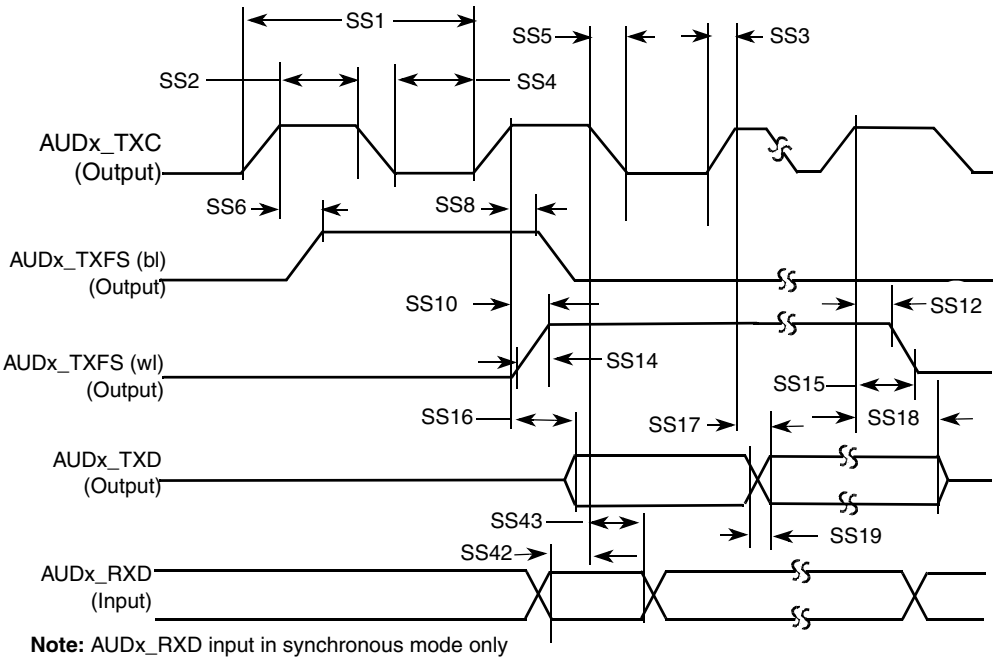


Figure 90. SSI Transmitter Internal Clock Timing Diagram

Table 96. 21 x 21 mm Functional Contact Assignments (continued)

Ball Name	Ball	Power Group	Ball Type	Out of Reset Condition[1]			
				Default Mode (Reset Mode)	Default Function (Signal Name)	Input/Output	Value[2]
EIM_DA6	K25	NVCC_EIM2	GPIO	ALT0	EIM_AD06	Input	PU (100K)
EIM_DA7	L25	NVCC_EIM2	GPIO	ALT0	EIM_AD07	Input	PU (100K)
EIM_DA8	L24	NVCC_EIM2	GPIO	ALT0	EIM_AD08	Input	PU (100K)
EIM_DA9	M21	NVCC_EIM2	GPIO	ALT0	EIM_AD09	Input	PU (100K)
EIM_DA10	M22	NVCC_EIM2	GPIO	ALT0	EIM_AD10	Input	PU (100K)
EIM_DA11	M20	NVCC_EIM2	GPIO	ALT0	EIM_AD11	Input	PU (100K)
EIM_DA12	M24	NVCC_EIM2	GPIO	ALT0	EIM_AD12	Input	PU (100K)
EIM_DA13	M23	NVCC_EIM2	GPIO	ALT0	EIM_AD13	Input	PU (100K)
EIM_DA14	N23	NVCC_EIM2	GPIO	ALT0	EIM_AD14	Input	PU (100K)
EIM_DA15	N24	NVCC_EIM2	GPIO	ALT0	EIM_AD15	Input	PU (100K)
EIM_EB0	K21	NVCC_EIM2	GPIO	ALT0	EIM_EB0_B	Output	1
EIM_EB1	K23	NVCC_EIM2	GPIO	ALT0	EIM_EB1_B	Output	1
EIM_EB2	E22	NVCC_EIM0	GPIO	ALT5	GPIO2_IO30	Input	PU (100K)
EIM_EB3	F23	NVCC_EIM0	GPIO	ALT5	GPIO2_IO31	Input	PU (100K)
EIM_LBA	K22	NVCC_EIM1	GPIO	ALT0	EIM_LBA_B	Output	1
EIM_OE	J24	NVCC_EIM1	GPIO	ALT0	EIM_OE	Output	1
EIM_RW	K20	NVCC_EIM1	GPIO	ALT0	EIM_RW	Output	1
EIM_WAIT	M25	NVCC_EIM2	GPIO	ALT0	EIM_WAIT	Input	PU (100K)
ENET_CRS_DV	U21	NVCC_ENET	GPIO	ALT5	GPIO1_IO25	Input	PU (100K)
ENET_MDC	V20	NVCC_ENET	GPIO	ALT5	GPIO1_IO31	Input	PU (100K)
ENET_MDIO	V23	NVCC_ENET	GPIO	ALT5	GPIO1_IO22	Input	PU (100K)
ENET_REF_CLK[3]	V22	NVCC_ENET	GPIO	ALT5	GPIO1_IO23	Input	PU (100K)
ENET_RX_ER	W23	NVCC_ENET	GPIO	ALT5	GPIO1_IO24	Input	PU (100K)
ENET_RXD0	W21	NVCC_ENET	GPIO	ALT5	GPIO1_IO27	Input	PU (100K)
ENET_RXD1	W22	NVCC_ENET	GPIO	ALT5	GPIO1_IO26	Input	PU (100K)
ENET_TX_EN	V21	NVCC_ENET	GPIO	ALT5	GPIO1_IO28	Input	PU (100K)
ENET_TXD0	U20	NVCC_ENET	GPIO	ALT5	GPIO1_IO30	Input	PU (100K)
ENET_TXD1	W20	NVCC_ENET	GPIO	ALT5	GPIO1_IO29	Input	PU (100K)
GPIO_0	T5	NVCC_GPIO	GPIO	ALT5	GPIO1_IO00	Input	PD (100K)
GPIO_1	T4	NVCC_GPIO	GPIO	ALT5	GPIO1_IO01	Input	PU (100K)
GPIO_16	R2	NVCC_GPIO	GPIO	ALT5	GPIO7_IO11	Input	PU (100K)
GPIO_17	R1	NVCC_GPIO	GPIO	ALT5	GPIO7_IO12	Input	PU (100K)
GPIO_18	P6	NVCC_GPIO	GPIO	ALT5	GPIO7_IO13	Input	PU (100K)
GPIO_19	P5	NVCC_GPIO	GPIO	ALT5	GPIO4_IO05	Input	PU (100K)
GPIO_2	T1	NVCC_GPIO	GPIO	ALT5	GPIO1_IO02	Input	PU (100K)
GPIO_3	R7	NVCC_GPIO	GPIO	ALT5	GPIO1_IO03	Input	PU (100K)

7 Revision History

Table 99 provides a revision history for the i.MX 6Dual/6Quad data sheet.

Table 99. i.MX 6Dual/6Quad Data Sheet Document Revision History

Rev. Number	Date	Substantive Change(s)
5	09/2017	Rev. 5 changes include the following: • Changed throughout: – Changed terminology from “floating” to “not connected”. – Removed VADC feature from 19mm x 19mm package. Contact NXP sales and marketing with enablement options. • Section 1, “Introduction” on page 1: Corrected A9 core speed from 1 GHz to 1.2 GHz. • Section 1.2, “Features” on page 5: Changed Internal/external peripheral item from “LVDS serial ports—One port up to 165 MPixels/sec…” to: “…—One port up to 170 MPixels/sec…”. • Table 1, “Example Orderable Part Numbers”: Added part numbers for 1.2 GHz extended commercial parts and silicon revision 1.4 with suffix “E”. • Section 1.3, “Signal Naming Convention” on page 8” and Section 6.1, “Signal Naming Convention”: changed wording from *updated* or *changed signal naming,* to *standard signal naming*. • Table 2, “i.MX 6Dual/6Quad Modules List,” on page 11: – Added bullet to uSDHC row: “Conforms to the SD Host Controller Standard Specification v3.0” • Table 2, “i.MX 6Dual/6Quad Modules List,” on page 11: Added DTCP module. • Section 4, “Electrical Characteristics” on page 20: Changed several references from JESD and JEDEC standards to cross references to the Section 4.10, “Multi-Mode DDR Controller (MMDC). • Table 4, “Absolute Maximum Ratings,” on page 21: Multiple changes: – Core supply voltages: Separated rows by LDO enabled and LDO bypass. For LDO enabled, changed maximum value from 1.5 to 1.6V. – Renamed Internal supply voltages to Core supply output voltage (LDO enabled) and changed maximum value from 1.3 to 1.4V. Added symbol NVCC_PLL_OUT. – Reordered VDD_HIGH_IN row and changed maximum value from 3.6 to 3.7V. – DDR I/O supply voltage row changes: — Changed Symbols from “Supplies denoted as I/O supply” to: “NVCC_DRAM” — Added footnote. – GPIO I/O supply voltage: Added symbols. Changed maximum value from 3.6 to 3.7V. – Resequenced: HDMI, PCIe, and SATA PHY high (VPH) supply voltage to precede low (VP) – Added row: RGMII I/O supply voltage – Added row, V_{in}/V_{out} input/output voltage range (non-DDR pins) distinguishing between DDR pins. – Changed maximum value for V_{in}/V_{out} input/output voltage range DDR pins to OVDD+0.4. – Added footnotes to both maximum values of V_{in}/V_{out} input/output voltage range. – Added row: USB_OTG_CHD_B • Table 6, “Operating Ranges,” on page 23: – Run Mode LDO enabled: VDD_ARM_IN; Added row for LDO Output Set Point of 1.275 V for operation up to1200 MHz. • Section 4.1.2, “Thermal Resistance” on page 22: Added NOTE: “Per JEDEC JESD51-2, the intent of thermal resistance measurements…”. • Section 4.1.5, “Maximum Measured Supply Currents” on page 26: Clarified language throughout this section regarding the use case to estimate the maximum supply current. • Section 4.2.1, “Power-Up Sequence” on page 33: – Removed content about calculating the proper current limiting resistor for a coin cell. – Removed inference to internal POR. • Section 4.5.2, “OSC32K” on page 37: Removed content about calculating the proper current limiting resistor for a coin cell. • Section 4.6.1, “XTALI and RTC_XTALI (Clock Inputs) DC Parameters” on page 39: – Added “NOTE: The Vil and Vih specifications only apply when an external clock source is used…”. *(Revision History table continues on next page.)*

Table 99. i.MX 6Dual/6Quad Data Sheet Document Revision History (continued)

Rev. Number	Date	Substantive Change(s)
5 (*Cont.*)	09/2017	• Table 21, "XTALI and RTC_XTALI DC Parameters," on page 39: – Added footnote to RTC_XTALI high level DC input voltage row: "This voltage specification must not be exceeded and …". Section 4.6.4, "RGMII I/O 2.5V I/O DC Electrical Parameters" on page 40: Added section and table. • Section 4.10, "Multi-Mode DDR Controller (MMDC)" on page 64: Replaced section with new content. Was: 4.9.4 "*DDR SDRAM Specific Parameters (DDR3/DDR3L/LPDDR2)*" with timing diagrams and parameter tables for DDR3/DDR3L/LPDDR2. • Table 51, "eMMC4.4/4.41 Interface Timing Specification," on page 81, – Corrected SD3, uSDHC Input Setup Time, minimum value from 2.6ns to 1.7ns. – Added footnote to Card Input Clock regarding duty cycle range. • Table 52, "SDR50/SDR104 Interface Timing Specification," on page 82: Changes to Min/Max values: – SD2 min from: 0.3 x tCLK; to: 0.46 x tCLK – SD2 max from: 0.7 x tCLK to: 0.54 x tCLK – SD3 min from: 0.3 x tCLK; to: 0.46 x tCLK. Also corrected ID from duplicate SD2 to SD3. – SD3 max from: 0.7 x tCLK; to: 0.54 x tCLK – SD5 max from: 1 ns; to: 0.74 ns • Table 62, "Camera Input Signal Cross Reference, Format, and Bits Per Cycle," on page 95: Changed RGB565, 16 bits column heading from 2 cycles to 1 cycle. • Table 63, "Sensor Interface Timing Characteristics," on page 98, Sensor Interface Timing characteristics: Added rows to include Vsync values. • Table 95, "21 x 21 mm Supplies Contact Assignment," on page 145: Added description to ZQPAD. • Table 96, "21 x 21 mm Functional Contact Assignments," on page 147: – Changed rows DRAM_SDCLK_0 and DRAM_SDCLK_1, Out of Reset Conditions from *"Input–Hi-Z"* to *"Output*–0". – Added description to GPANAIO row: "…output for NXP use only…" *(Revision History table continues on next page.)*